

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® S series is optimized for its switching characteristics to achieve aggressive EMI standards. It is easy to use for smaller power supply systems to meet the both efficiency and EMI standards.

## Features

- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- LED lighting
- Charger
- Adapter
- Telecom power
- Server power
- Solar/UPS



## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_j(max)$	700	V
$I_D, pulse$	33	A
$R_{DS(ON), max} @ V_{GS}=10V$	380	mΩ
$Q_g$	20.6	nC

## Marking Information

Product Name	Package	Marking
OSG65R380FSF	TO220F_NL	OSG65R380FS

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_D$	11	A
Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$		7	
Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	33	A
Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_S$	11	A
Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	33	A
Power dissipation <sup>3)</sup> , $T_C=25\text{ }^\circ\text{C}$	$P_D$	31	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	211	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$ , $I_{SD}\leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	4	$^\circ\text{C/W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	650			V	$V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$
		700				$V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$ , $T_j=150\text{ }^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	2.9		3.9	V	$V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.30	0.38	$\Omega$	$V_{GS}=10\text{ V}$ , $I_D=5.5\text{ A}$
			0.75			$V_{GS}=10\text{ V}$ , $I_D=5.5\text{ A}$ , $T_j=150\text{ }^\circ\text{C}$
Gate-source leakage current	$I_{GS}$			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=650\text{ V}$ , $V_{GS}=0\text{ V}$
Gate resistance	$R_G$		16		$\Omega$	$f=1\text{ MHz}$ , Open drain

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		875.2		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		94.8		pF	
Reverse transfer capacitance	C <sub>rss</sub>		2.9		pF	
Turn-on delay time	t <sub>d(on)</sub>		25.7		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, R <sub>G</sub> =2.5 Ω, I <sub>D</sub> =10 A
Rise time	t <sub>r</sub>		25.9		ns	
Turn-off delay time	t <sub>d(off)</sub>		58.4		ns	
Fall time	t <sub>f</sub>		21		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		20.6		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, I <sub>D</sub> =10 A
Gate-source charge	Q <sub>gs</sub>		6.7		nC	
Gate-drain charge	Q <sub>gd</sub>		6.3		nC	
Gate plateau voltage	V <sub>plateau</sub>		5.7		V	

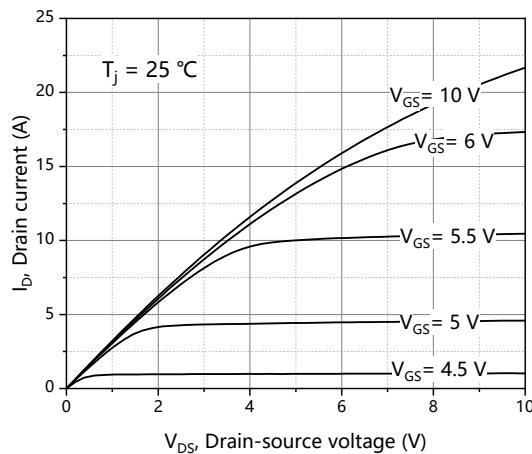
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =11 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		306.7		ns	V <sub>R</sub> =400 V, I <sub>S</sub> =10 A, di/dt=100 A/μs
Reverse recovery charge	Q <sub>rr</sub>		3.7		μC	
Peak reverse recovery current	I <sub>rrm</sub>		21.5		A	

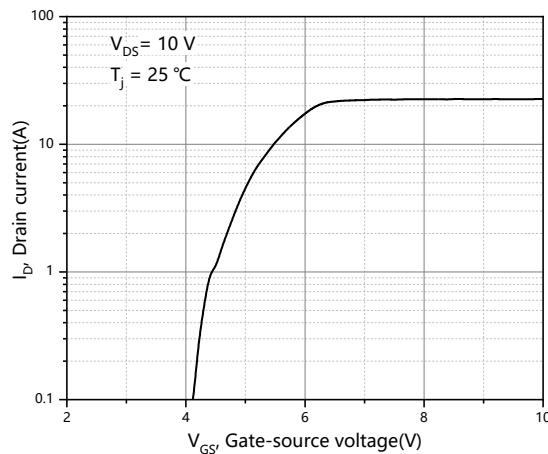
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=79.9 mH, starting T<sub>j</sub>=25 °C.

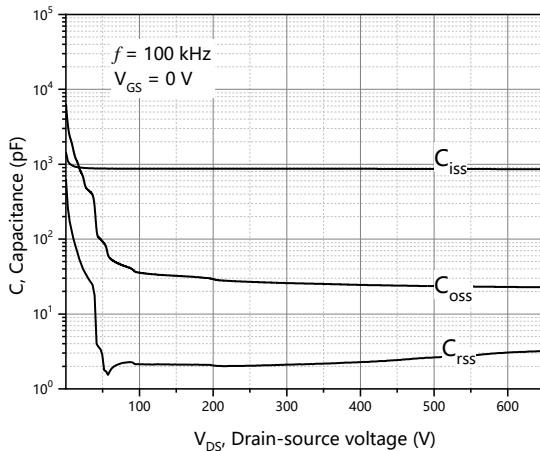
## Electrical Characteristics Diagrams



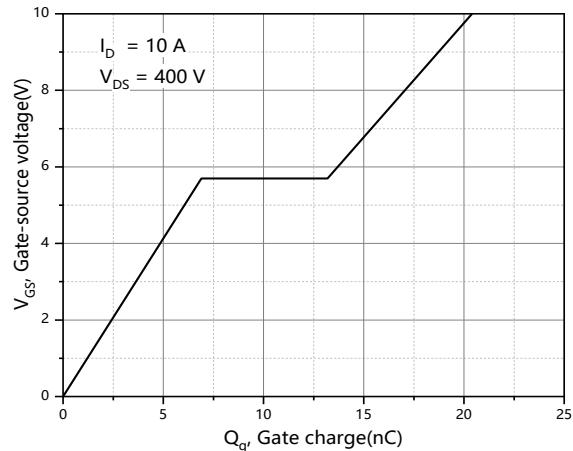
**Figure 1. Typ. output characteristics**



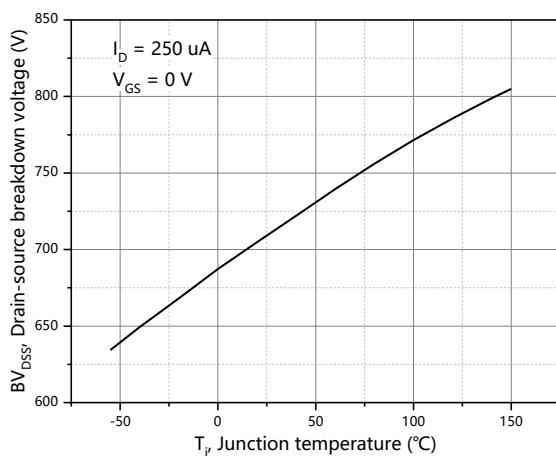
**Figure 2. Typ. transfer characteristics**



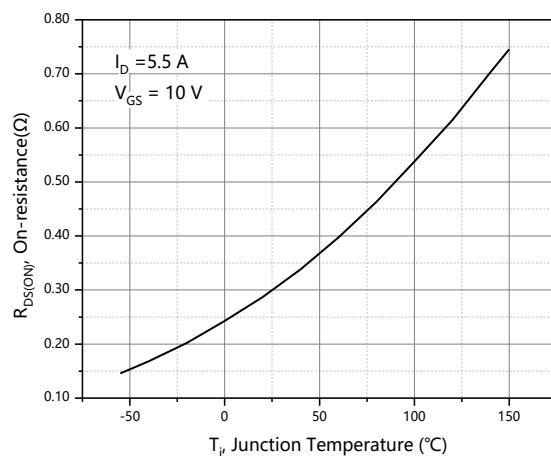
**Figure 3. Typ. capacitances**



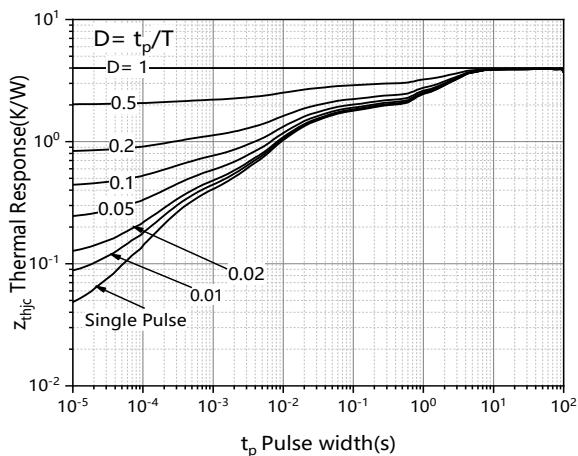
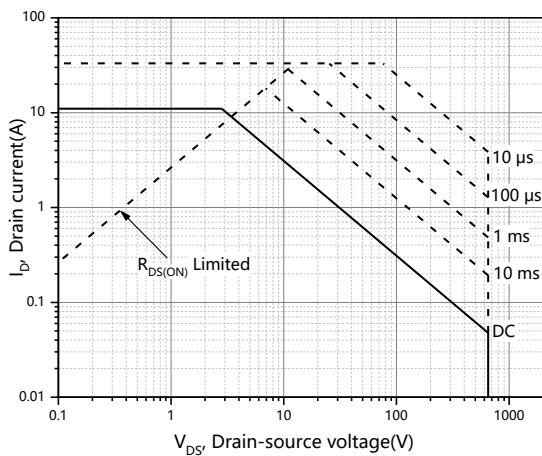
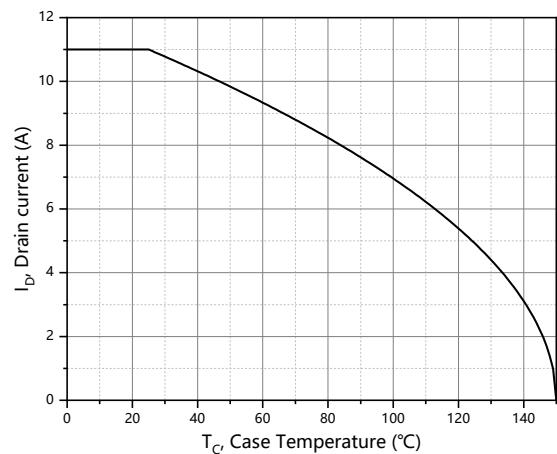
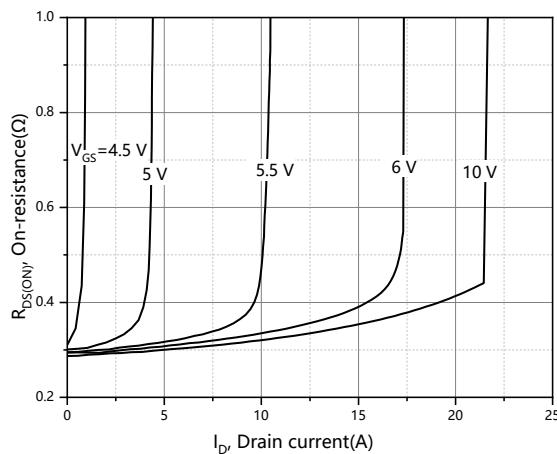
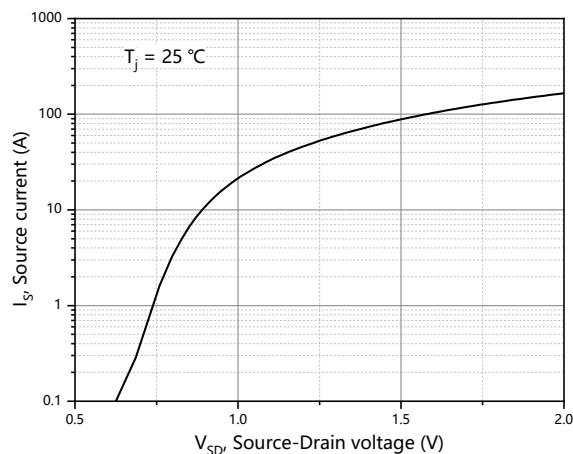
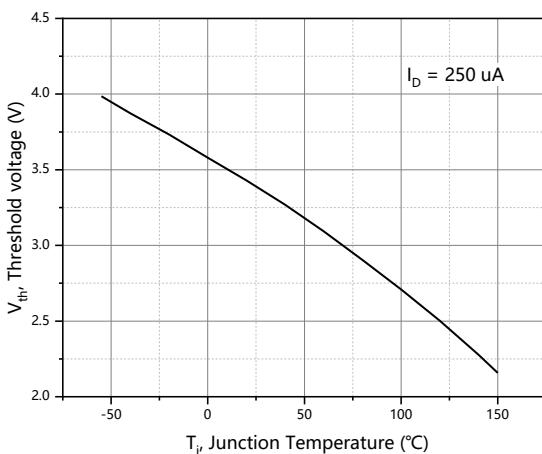
**Figure 4. Typ. gate charge**

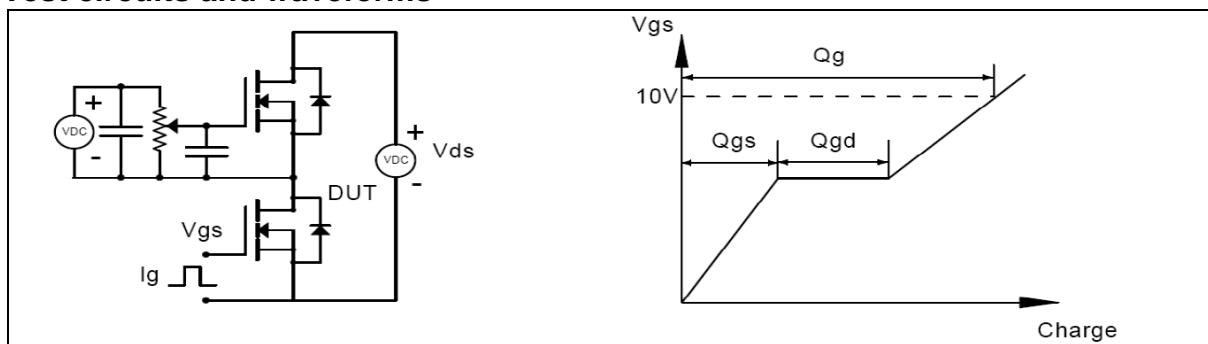
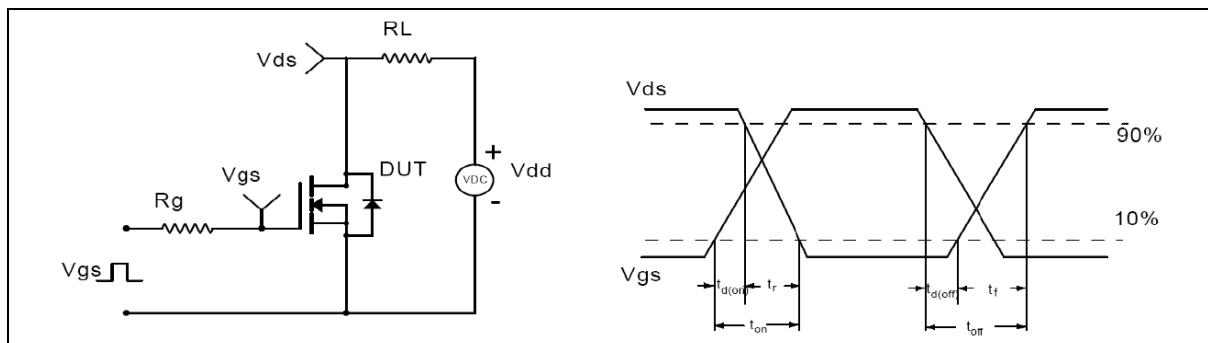
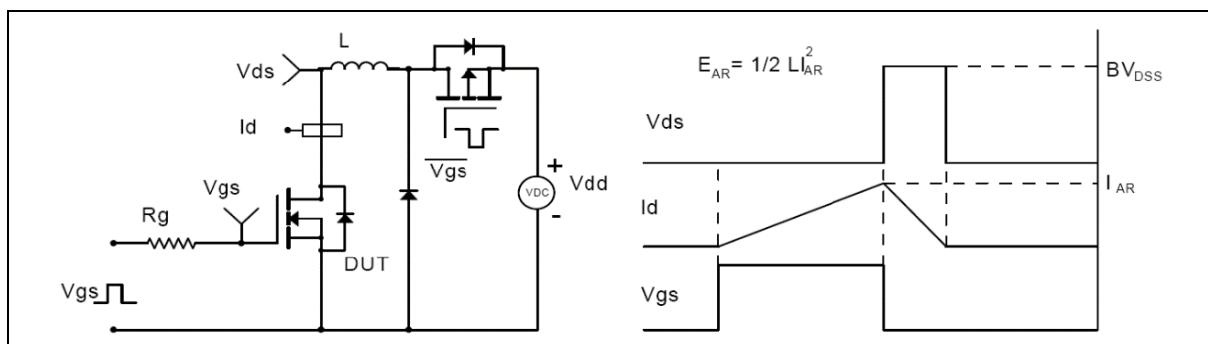
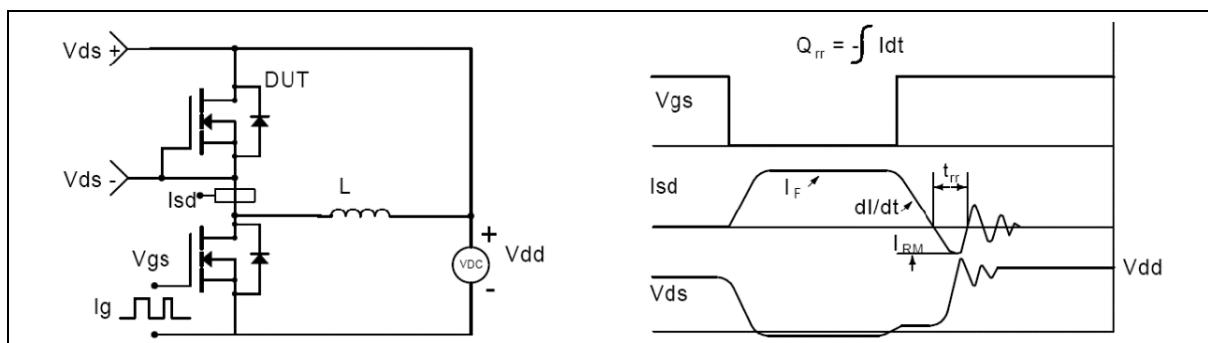


**Figure 5. Drain-source breakdown voltage**

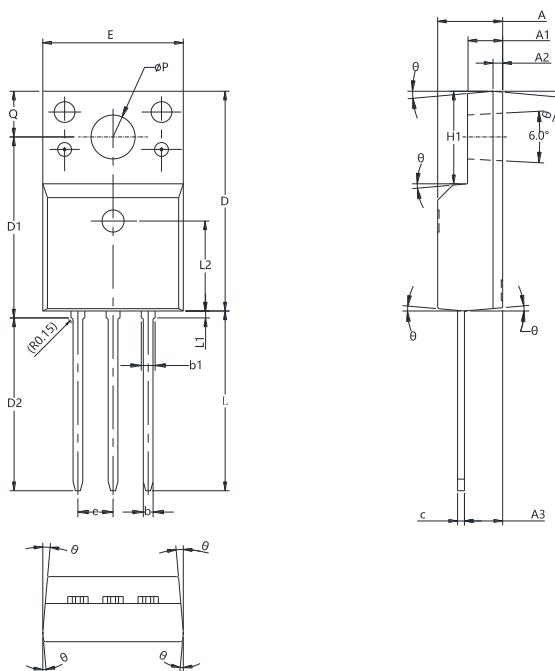


**Figure 6. Drain-source on-state resistance**



**Test circuits and waveforms**

**Figure 1. Gate charge test circuit & waveform**

**Figure 2. Switching time test circuit & waveforms**

**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**

**Figure 4. Diode reverse recovery test circuit & waveforms**

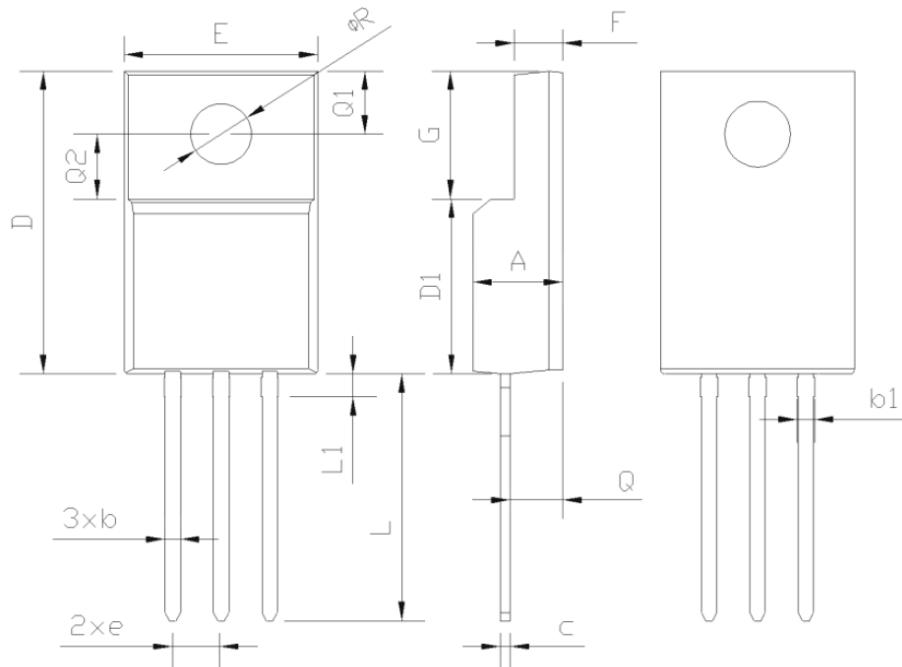
## Package Information



Symbol	mm		
	Min	Nom	Max
A	4.5	4.7	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
b	0.6	-	0.8
b1	0.9	-	1.1
c	0.45	0.5	0.6
D	15.67	15.87	16.07
D1	12.87	13.07	13.27
D2	12.28	12.48	12.68
E	9.96	10.16	10.36
e	2.54 BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	-	-	0.85
L2	6.50 REF		
ΦP	3.08	3.18	3.28
Q	3.20	-	3.40
θ1	1°	3°	5°

Version1: TO220F\_NL-J package outline dimension

## Package Information



Symbol	mm		
	Min	Nom	Max
A	4.30	4.50	4.70
b	0.60	0.70	0.80
b1	0.60	0.80	0.90
c	0.45	0.50	0.60
D	14.70	15.00	15.30
D1	8.50 REF		
e	2.60 BSC		
E	9.70	10.00	10.30
F	2.50	2.70	2.90
G	6.30	6.50	6.70
L	13.40	13.60	13.80
L1	1.00	1.10	1.20
Q	2.50	2.60	2.70
Q1	2.90	3.00	3.10
Q2	3.50 REF		
ΦR	3.00	3.20	3.40

Version2: TO220F\_NL-M package outline dimension

## Ordering Information

Package Type	Units/Tube	Tubes / Inner Box	Units/ Inner Box	Inner Box/ Carton Box	Units/ Carton Box
TO220F_NL-J	50	20	1000	5	5000
TO220F_NL-M	50	40	2000	4	8000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R380FSF_NB	TO220F_NL	yes	yes	yes

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